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Application ID: 10680280  
Title of Invention: SEMICONDUCTOR PACKAGE AND  
METHOD FOR MANUFACTURING  
THE SAME  
First Named Inventor: Jong Paek  
Domestic/Foreign Application: Domestic Application  
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Attorney Docket Number: AMKOR021G



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Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
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# TRANSMITTAL

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Stylesheet Version v1.1.0


Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME									
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids5-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids5-usidst.xml		us-ids.dtd		us-ids.xsl
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Comments										



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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<p>Application Number: 10/680280 </p> <p>Confirmation Number: 7297</p> <p>First Named Applicant: Jong Paek</p> <p>Attorney Docket Number: AMKOR021G</p> <p>Art Unit: 2811</p> <p>Search string: ( 6194777 or 6198171 or 6197615 or 6201292 or 6201186 or 6204554 or 6208023 or 6208021 or 6208020 or 6211462 or 6218731 or 6222258 or 6225146 or 6229205 or 6229200 or 6239384 or 6239367 or 6242281 or 6256200 or 6258629 or 6282095 or 6281568 or 6281566 or 6285075 or 6291273 or 6291271 or 6294830 or 6294100 or 6297548 or 6295977 or 6303997 or 6303984 or 6307272 or 6309909 or 6316838 or 6316822 or 6323550 or 6326678 or 6326244 or 6326243 or 6335564 or 6337510 or 6339255 or 6348726 or 6355502 or 6369454 or 6369447 or 6373127 or 6380048 or 6384472 ).pn.</p> <p><b>US Patent Documents</b></p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>6194777</td><td>2001-02-27</td><td>ABBOTT ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>6198171</td><td>2001-03-06</td><td>HUANG ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>6197615</td><td>2001-03-06</td><td>SONG ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>6201292</td><td>2001-03-13</td><td>YAGI ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>6201186</td><td>2001-03-13</td><td>DANIELS ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>6204554</td><td>2001-03-20</td><td>EWER ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>6208023</td><td>2001-03-27</td><td>NAKAYAMA ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>6208021</td><td>2001-03-27</td><td>OHUCHI ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>9</td><td>6208020</td><td>2001-03-27</td><td>MINAMIO</td><td></td><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	6194777	2001-02-27	ABBOTT ET AL					2	6198171	2001-03-06	HUANG ET AL					3	6197615	2001-03-06	SONG ET AL					4	6201292	2001-03-13	YAGI ET AL					5	6201186	2001-03-13	DANIELS ET AL					6	6204554	2001-03-20	EWER ET AL					7	6208023	2001-03-27	NAKAYAMA ET AL					8	6208021	2001-03-27	OHUCHI ET AL					9	6208020	2001-03-27	MINAMIO			
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	36	6316822	2001-11-13	VENKATESHWARAN ET AL.
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	40	6326243	2001-12-04	SUZUYA ET AL.
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	47	6369447	2002-04-09	MORI
	48	6373127	2002-04-16	BAUDOUIN ET AL.
	49	6380048	2002-04-30	BOON ET AL.
	50	6384472	2002-05-07	HUANG

Signature

Examiner Name	Date